PCN Number:	20151028000		**PCN Date:**	2/4/2016
Title:	Datasheet for TPS65218, TPS65218B101			
Customer Contact:	PCN Manager		**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.

TEXAS INSTRUMENTS

TPS65218

SLDS206B – NOVEMBER 2014 – REVISED FEBRUARY 2016

Changes from Revision A (September 2015) to Revision B   Page

Changes from Original (November 2014) to Revision A   Page

The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS65218, TPS65218B101	SLDS206	**SLDS206B**

These changes may be reviewed at the datasheet links provided.
http://www.ti.com/product/TPS65218

Reason for Change:
To more accurately reflect device characteristics.
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.
Changes to product identification resulting from this PCN:
None.
Product Affected:

TPS65218B101PHPR	TPS65218B101PHPT	TPS65218B1PHPR	TPS65218B1PHPT
TPS65218B1RSLR	TPS65218B1RSLT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com